



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20190820010
Datasheet for CDCUN1208LP
Information Only**

Date: September 13, 2019
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN team (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services


Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
CDCUN1208LPRHBT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20190820010	PCN Date:	Sept. 13, 2019																																
Title:	Datasheet for CDCUN1208LP																																		
Customer Contact:	PCN Manager	Dept:	Quality Services																																
Change Type:																																			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site																																	
<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material																																	
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process																																	
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Site																																	
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials																																	
		<input type="checkbox"/> Wafer Fab Process																																	
Notification Details																																			
Description of Change:																																			
<p>Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.</p>																																			
		CDCUN1208LP <small>SCAS928D – MAY 2012 – REVISED APRIL 2019</small>																																	
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The datasheet number will be changing.																																			
Device Family	Change From:	Change To:																																	
CDCUN1208LP	SCAS928C	SCAS928D																																	
These changes may be reviewed at the datasheet links provided.																																			
http://www.ti.com/product/CDCUN1208LP																																			
Reason for Change:																																			
To accurately reflect device characteristics.																																			
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):																																			
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.																																			
Changes to product identification resulting from this PCN:																																			
None.																																			

Product Affected:			
CDCUN1208LPRHBR	CDCUN1208LPRHBT		

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

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